

2022.5.6 News Release

Order received for “Solder Ball Mounter System” from Major Semiconductor Manufacturer in U.S.A.

(To be capable for advanced semiconductor packages)

We, AIMECHATEC, Ltd. (Head Office: Koyodai, Ryugasaki-shi, Ibaraki-pref. President: Isao Abe) are pleased to announce that we received order for full line of “Solder Ball Mounter System” from Major Semiconductor Manufacturer in the U.S.A.

Now that computers have evolved from PCs to mobile devices and entered the AI era, the roles of semiconductor packaging has changed drastically. Based on the needs such as large capacity, high speed communication, and low power consumption, semiconductor manufacturers are focusing on the development of high-performance packaging technologies including multi-chip and 3D stacking, in addition to the technology development for miniaturization Process.

We proposed New Model G-series incorporating Ball Mount Technologies with system integration technologies being cultivated through our mass production equipment for Flat Panel Display. As a result, we received high praise and the order from the customer.

For advanced semiconductor packages requiring high-performance packaging technologies, the needs for high quality and high yield are greater, and then our equipment that can improve yield rate is considered to be adopted. We expect that this equipment will contribute to our further expansion of semiconductor businesses in the future.

We will continue to contribute to the society by improving convenient and affluent lifestyle through our technological innovations for manufacturing processes.

Your continued kind support to our company is sincerely appreciated.

Contact:

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<https://www.ai-mech.com/>